

Serial Nr.: 09/209,634  
Art Unit: 2811



UPA-98165

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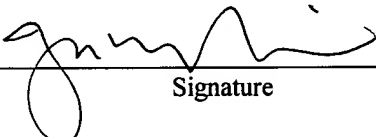
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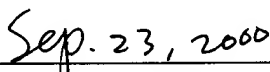
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **09/209,634** Examiner: **Luan Thai**  
Inventor: **Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang,  
Randy Hsiao-Yu Lo and Chiang-Han Day**  
Filed: **December 10, 1998** Art Unit: **2811**  
Title: **Flip-Chip Ball Grid Array Package With A Heat Slug**

Certificate of Mailing

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SUBMISSION OF FORMAL DRAWINGS

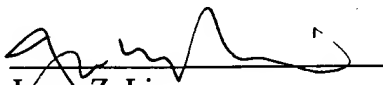
Assistant Commissioner For Patents  
Washington, D.C. 20231

Attn.: Chief Draftsperson

Sir:

Enclosed are **ten** sheets of the formal drawings for FIGs. **1-8** for correcting informalities and filing in the above-identified U.S. patent application.

Respectfully submitted,

  
\_\_\_\_\_  
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